

# Quad 8-Bit CMOS D/A Converter with Internal 10 V Reference

**DAC-8426** 

### 1.1 Scope.

This specification covers the detail requirement for a quad 8-bit CMOS digital-to-analog converter with output voltage amplifiers and internal 10 V voltage reference. The internal latches provide direct interface for most microprocessors. The DAC-8426 operates with either a dual or single power supply.

It is highly recommended that this data sheet be used as a baseline for new military or aerospace specification control drawings.

#### 1.2 Part Number.

The complete part numbers per Table 1 of this specification is as follows:

Device Part Number Package
-1 DAC-8426AR/883 R

#### 1.2.3 Case Outline.

Letter Case Outline (Lead Finish per MIL-M-38510)

R 20-Lead Ceramic Dual-in-Line Package (Cerdip)

### 1.3 Absolute Maximum Ratings. $(T_A = +25^{\circ}C \text{ unless otherwise noted})$

• \ n	
V <sub>DD</sub> to AGND or DGND	0.3 V, +17 V
V <sub>SS</sub> to AGND or DGND	$\cdots \cdots -7$ V, $V_{DD}$
$V_{DD}$ to $V_{SS}$	$\cdots \cdots $
AGND to DGND	$\cdots \cdots -0.3 \text{ V}, +5 \text{ V}$
Digital Input Voltage to DGND	$\dots \dots $
V <sub>REFOUT</sub> to AGND	$\cdots \cdots -0.3 \text{ V}, \text{ V}_{DD}$
V <sub>OUT</sub> to AGND	$V_{SS}$ , $V_{DD}$
Power Dissipation to +75°C	500 mW
Derate above 75°C by	
Operating Temperature Range	
Junction Temperature Range (T <sub>J</sub> )	65°C to +150°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (Soldering 60 sec)	+300°C

#### 1.5 Thermal Characteristics.

Thermal Resistance  $\theta_{JC} = 7^{\circ}\text{C/W}$  $\theta_{JA} = 70^{\circ}\text{C/W max}$ 

## DAC-8426 — SPECIFICATIONS

Table 1.

		Device	Limits		Group A		
Test	Symbol	Types	Min	Max	Subgroups	Conditions <sup>1</sup>	Units
Resolution	N	All	8		1, 2, 3	$T_A = +25^{\circ}C, -55^{\circ}C \& +125^{\circ}C$	Bits
Total Unadjusted Error	TUE	-1		±1	1, 2, 3	Includes Reference <sup>2</sup>	LSB
		-2		±2	1, 2, 3	$T_A = +25^{\circ}C, -55^{\circ}C \& +125^{\circ}C$	
Relative Accuracy	INL	-1		±1/2	1, 2, 3	$T_A = +25^{\circ}C, -55^{\circ}C \& +125^{\circ}C$	LSB
		-2		±1	1, 2, 3		
Differential Nonlinearity	DNL	All		±1	1, 2, 3	Note 3; $T_A = +25^{\circ}C$ , $-55^{\circ}C$ & $+125^{\circ}C$	LSB
Zero Scale Error	V <sub>ZSE</sub>	All		20	1, 2, 3	$V_{SS} = -5 \text{ V};$ $T_A = +25^{\circ}\text{C}, -55^{\circ}\text{C \& } +125^{\circ}\text{C}$	mV
Reference Output Voltage	V <sub>REFOUT</sub>	-1	9.96	10.04	1, 2, 3	No Load;	V
		-2	9.92	10.08		$T_A = +25^{\circ}C, -55^{\circ}C \& +125^{\circ}C$	
Reference Load Regulation	$LD_{REG}$	All		0.1	1, 2, 3	$\Delta I_L = 10 \text{ mA};$ $T_A = +25^{\circ}\text{C}, -55^{\circ}\text{C \& } +125^{\circ}\text{C}$	%/mA
Reference Line Regulation	LN <sub>REG</sub>	All		0.04	1, 2, 3	$\Delta V_{DD} = \pm 10\%;$ $T_A = +25^{\circ}C, -55^{\circ}C \& +125^{\circ}C$	%/mA
Reference Output Current	I <sub>REFOUT</sub>	All	5		1, 2, 3	$\Delta V_{REFOUT} < 40 \text{ mV};$ $T_A = +25^{\circ}\text{C}, -55^{\circ}\text{C \& } +125^{\circ}\text{C}$	
Logic Input "0"	V <sub>INL</sub>	All		0.8	1, 2, 3	$T_A = +25^{\circ}C, -55^{\circ}C \& +125^{\circ}C$	V
Logic Input "1"	V <sub>INH</sub>	All	2.4		1, 2, 3	$T_A = +25^{\circ}C, -55^{\circ}C \& +125^{\circ}C$	V
Logic Input Current	I <sub>IN</sub>	All		10	1, 2, 3	$V_{IN} = 0 \text{ V or } V_{DD};$ $T_A = +25^{\circ}\text{C}, -55^{\circ}\text{C \& } +125^{\circ}\text{C}$	μА
Positive Supply Current <sup>3</sup>	$I_{DD}$	All		14	1, 2, 3	$T_A = +25^{\circ}C, -55^{\circ}C \& +125^{\circ}C$	mA
Negative Supply Current <sup>3</sup>	I <sub>ss</sub>	All		10	1, 2, 3	Dual Supply, $V_{SS} = -5 \text{ V}$ ; $T_A = +25^{\circ}\text{C}, -55^{\circ}\text{C} & +125^{\circ}\text{C}$	mA
Power Supply Sensitivity	PSS	All		0.01	1, 2, 3	$\Delta V_{DD} = \pm 10\%;$ $T_A = +25^{\circ}C, -55^{\circ}C \& +125^{\circ}C$	%/%
Output Source Current	I <sub>OUT</sub>	All	10		1, 2, 3	Digital Inputs All Ones; T <sub>A</sub> = +25°C, -55°C & +125°C	mA
Output Sink Current	I <sub>OUT</sub> -	All	0.35		1, 2, 3	Digital Inputs All Zeros	mA
V <sub>OUT</sub> Settling Time (Positive or Negative)	t <sub>S</sub>	All		5	9	To $\pm 1/2$ LSB; $T_A = +25^{\circ}C$	μs
Address to Write Setup Time	t <sub>AS</sub>	All	0		9, 10, 11	$T_A = +25^{\circ}C, -55^{\circ}C \& +125^{\circ}C$	ns
Address to Write Hold Time	t <sub>AH</sub>	All	0		9, 10, 11	$T_A = +25^{\circ}C, -55^{\circ}C \& +125^{\circ}C$	ns
Data Valid to Write Setup Time	t <sub>DS</sub>	All	70		9, 10, 11	$T_A = +25^{\circ}C, -55^{\circ}C \& +125^{\circ}C$	ns
Data Valid to Write Hold Time	t <sub>DH</sub>	All	10		9, 10, 11	$T_A = +25^{\circ}C, -55^{\circ}C \& +125^{\circ}C$	ns
Write Pulse Width	t <sub>WR</sub>	All	50		9, 10, 11	$T_A = +25^{\circ}C, -55^{\circ}C \& +125^{\circ}C$	ns
Minimum Load Resistance	R <sub>L(MIN)</sub>	All	2		1, 2, 3	Digital Inputs All Ones; T <sub>A</sub> = +25°C, -55°C & +125°C	kΩ
V <sub>OUT</sub> Slew Rate	SR	All	2.5		7	$T_A = +25^{\circ}C$	V/µs

NOTES  $^{1}V_{DD}=+15~V\pm10\%,~AGND=0~V,~DGND=0~V,~V_{SS}=0~V$  unless otherwise specified.  $^{2}Includes~full-scale~error,~relative~accuracy,~and~zero~code~error.$   $^{3}Digital~inputs~V_{IN}=V_{INL}~or~V_{INH};~V_{OUT}~and~V_{REFOUT}~unloaded.$ 

Table 2. Electrical Test Requirements for Class B Devices

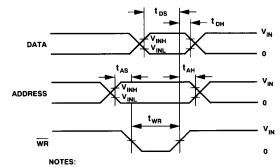
MIL-STD-883 Test Requirements	Subgroups (See Table 3)		
Interim Electrical Parameters (Pre Burn-In)	1		
Final Electrical Test Parameters	1,* 2, 3		
Group A Test Requirements	1, 2, 3, 7, 9, 10, 11		

### NOTE

Table 3. Control Table

Logi	Logic Control WR A1 A0		DAC-8426 Operation		
WR					
H	X	X	No Operation		
			Device Not Selected		
L	L	L	DAC A Transparent		
<u>_</u>	L	L	DAC A Latched		
L	L	Н	DAC B Transparent		
<u></u>	L	Н	DAC B Latched		
L	Н	L	DAC C Transparent		
<u>_</u>	Н	L	DAC C Latched		
L	Н	Н	DAC D Transparent		
<u></u>	Н	Н	DAC D Latched		

L = Low State, H = High State, X = Don't Care.



- 1. ALL INPUT SIGNAL RISE AND FALL TIMES ARE MEASURED FROM THE 10% TO 90% OF  $V_{DD}$  ( $t_r = t_f = 20$ ns OVER THE  $V_{DD}$  RANGE)
- 2. TIMING REFERENCE LEVEL IS FROM V<sub>INH</sub> + V<sub>INL</sub>

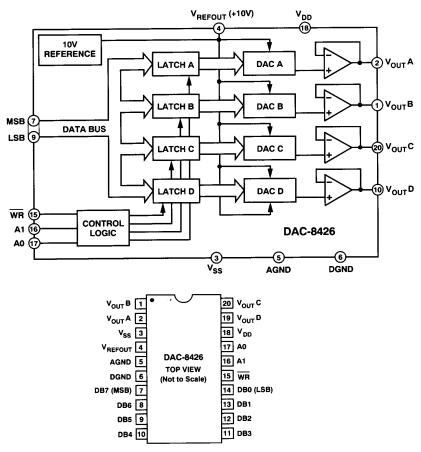
3. V<sub>IN</sub> = 5V

Write Timing Diagram

<sup>\*</sup>PDA applies to Subgroup 1 only. No other subgroups are included in PDA.

### **DAC-8426**

### 3.2.1 Functional Block Diagram and Terminal Assignments.

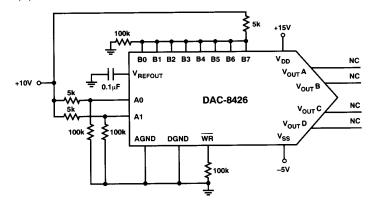


### 3.2.4 Microcircuit Technology Group.

This microcircuit is covered by technology group 80.

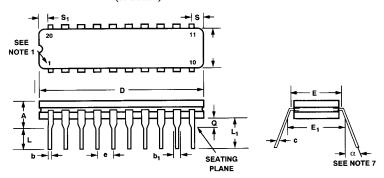
### 4.2.1 Life Test/Burn-In Circuit.

Steady state life test is per MIL-STD-883 Method 1005. Burn-in is per MIL-STD-883 Method 1015 test condition (B).



### 20-Lead Ceramic DIP

(R Suffix)



20-Lead Ceramic DIP (R Suffix)

	INCHES		MILLIMETERS		
SYMBOL	MIN	MAX	MIN	MAX	NOTES
Α		0.200		5.08	
b	0.014	0.023	0.36	0.58	
b <sub>1</sub>	0.030	0.070	0.76	1.78	2
С	0.008	0.015	0.20	0.38	
D		1.060		26.92	4
E	0.220	0.310	5.59	7.87	4
E <sub>1</sub>	0.290	0.320	7.37	8.13	7
е	0.100 BSC		2.54 BSC		5
L	0.125	0.200	3.18	5.08	
L <sub>1</sub>	0.150		3.81		
a	0.015	0.060	0.38	1.52	3
S		0.080		2.03	6
Sı	0.005		0.13		6
α	0°	15°	0°	15°	

### NOTES

- 1. Index area; a notch or a lead one identification mark is located adjacent to lead one.
- The minimum limit for dimension b<sub>1</sub> may be 0.023" (0.58 mm) for all four corner leads only.
- 3. Dimension  ${\bf Q}$  shall be measured from the seating plane to the base plane.
- 4. This dimension allows for off-center lid, meniscus and glass overrun.
- 5. The basic lead spacing is 0.100" (2.54 mm) between centerlines.
- 6. Applies to all four corners.
- 7. Leads center when  $\alpha$  is 0°. E<sub>1</sub> shall be measured at the centerline of the leads.

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